Max PCB Size 650×480mm Semi Automatic BGA Rework Station Featuring Temperature Control Upper Lower Independent Heating and Total Power 7500W for Rework

Our Product Introduction

Basic Information

- Brand Name: Wisdomshow
- Certification: CE
- Model Number: WDS-800E
- Minimum Order Quantity: 1
- Packaging Details: Wooden Case
- Delivery Time: 3-5days
- Payment Terms: TT
- Supply Ability: 200Sets / Month



Product Specification

- Placement Accuracy: ±0.02mm
- Max PCB Size: 650×480mm
- Thermocouple Ports: 5 Pcs
- Applicable Chip Size: 0.6×0.6mm-80×80mm
- Total Power: 7500W
- Temperature Control: Closed-loop K-type Thermocouple, Upper & Lower Independent Heating, ±1°C Accuracy
- Power Supply: AC220V±10%, 50/60Hz



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Product Description

Product Description:

The Semi Automatic BGA Rework Station is a state-of-the-art solution designed for precise and efficient soldering and desoldering of Ball Grid Array (BGA) components. This advanced station integrates cutting-edge technology to ensure accuracy, reliability, and ease of use, making it an essential tool for electronics repair professionals and manufacturing environments.

One of the standout features of this BGA rework station is its sophisticated temperature control system. Equipped with a closed-loop K-type thermocouple, the station provides highly accurate temperature regulation with a remarkable ±1°C accuracy. This precision is critical for delicate BGA components, ensuring optimal heating without the risk of thermal damage. Additionally, the unit features upper and lower independent heating elements, allowing for customized temperature settings on both sides of the PCB. This dual-zone heating capability enhances the quality of rework by providing uniform heat distribution and reducing thermal stress on components.

The station is also equipped with five thermocouple ports, enabling comprehensive temperature monitoring across various points during the rework process. This multi-point temperature sensing facilitates greater control and adaptability, supporting complex rework tasks that require meticulous thermal management.

Accuracy in component placement is paramount when dealing with BGAs, and this rework station excels in this regard. It boasts an exceptional placement accuracy of ±0.02mm, ensuring that components are perfectly aligned before soldering. This high level of precision minimizes the risk of soldering defects such as bridging or insufficient solder joints, thereby improving the overall reliability of repaired devices.

Powering this advanced equipment is a robust total power capacity of 7500W, delivered through a stable AC220V ±10% power supply operating at 50/60Hz. This powerful configuration ensures rapid heating and consistent temperature maintenance, reducing downtime and increasing throughput in repair or production workflows.

Another key component of this system is the infrared preheating table, which plays a crucial role in the rework process. The infrared preheating table evenly heats the PCB from below, preparing the board and components for the precise application of heat from the upper heating elements. This preheating step is vital for preventing thermal shock and warping, which can occur if the board temperature is unevenly or insufficiently raised. By incorporating the infrared preheating table, the BGA rework station significantly enhances the quality and safety of the rework process.

Overall, the Semi Automatic BGA Rework Station combines powerful heating capabilities, precise temperature control, and exceptional placement accuracy to deliver superior performance. Its integration of an infrared preheating table further elevates its effectiveness, making it an indispensable tool for any facility involved in BGA rework or advanced electronics repair. Whether used in a high-volume manufacturing environment or a specialized repair workshop, this station offers reliability, precision, and efficiency, ensuring that every rework job is completed to the highest standards.

Features:

Product Name: Semi Automatic BGA Rework Station

Max PCB Size: 650*480mm, suitable for large boards

Temperature Control: Closed-loop K-type Thermocouple with upper & lower independent heating

Temperature Accuracy: ±1°C for precise cpu repair

Thermocouple Ports: 5 Pcs for accurate temperature monitoring

Power Supply: AC220V±10%, 50/60Hz

Placement Accuracy: ±0.02mm ensuring high precision in BGA rework station operations

Ideal for efficient and reliable cpu repair tasks

Designed to enhance productivity in BGA rework station applications

Technical Parameters:

Power Supply	AC220V±10%, 50/60Hz
Total Power	7500W
Applicable Chip Size	0.6*0.6mm - 80*80mm
Temperature Control	Closed-loop K-type Thermocouple, Upper & Lower Independent Heating, ±1°C Accuracy
Thermocouple Ports	5 Pcs
Max PCB Size	650*480mm
Placement Accuracy	±0.02mm
Heating Zones	Three heating zone with Infrared preheating table
Operation Mode	Semi automatic

Applications:

The Wisdomshow WDS-800E Semi Automatic BGA Rework Station is an advanced and reliable solution designed for precise and efficient soldering and rework tasks. Originating from Shenzhen, China, this CE-certified product combines cutting-edge technology with user-friendly features to meet the demands of electronics repair professionals and manufacturing environments. Its robust design, supplied in a sturdy wooden case, ensures safe transportation and storage. With a minimum order quantity of just one unit and a supply ability of 200 sets per month, the WDS-800E is readily available with a swift delivery time of 3-5 days, and payment terms via TT facilitate

seamless transactions.
This rework station is ideal for a variety of product application occasions and scenarios, particularly in the field of motherboard repair. The station's infrared preheating table ensures uniform and controlled heating, reducing thermal stress on delicate components and improving soldering quality. Equipped with three heating zones, the WDS-800E allows precise temperature control for both upper and lower heating elements, providing independent closed-loop K-type thermocouple regulation with ±1°C accuracy. This feature guarantees optimal thermal management, crucial for complex BGA components and multilayer PCBs.
The WDS-800E supports a maximum PCB size of 650*480mm, making it suitable for a wide range of electronic devices from consumer electronics to industrial control boards. Its placement accuracy of ±0.02mm ensures that components are positioned with high precision, essential for fine-pitch BGA packages and other surface-mounted devices. The station includes 5 thermocouple ports, enabling detailed temperature monitoring across different zones and ensuring consistent reflow profiles tailored to specific repair or assembly requirements.
In practical scenarios, this semi-automatic BGA rework station excels in repairing and reworking motherboards for smartphones, laptops, gaming consoles, and other high-value electronics. It is also widely used in prototyping, small-batch production, and quality control processes where precision and repeatability are paramount. The combination of infrared preheating, three heating zones, and advanced temperature control makes the Wisdomshow WDS-800E an indispensable tool for technicians and engineers aiming to reduce rework time, improve solder joint reliability, and extend the lifespan of electronic assemblies.

Shenzhen Wisdomshow Technology Co.,ltd

+86 18926538696 elysia.li@wdsbga.cn bgaxraymachine.com

No. 3 Kangtai 3rd Road, Shatou Community, Shajing Street, Bao'an District, Shenzhen, China